A 6-bit 5.12-GS/s Flash ADC with Track-and-Hold Embedded Dynamic Preamplifier in 28nm CMOS

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As emerging applications require a high data-rate communication, ADCs for these systems should have a multi-GHz signal bandwidth [1]. Typically, a flash ADC is the most widely used structure for the 2022. GHz ADC thanks to 2^N-1 comparators deployed in parallel for an Nbit operation. Flash ADCs usually adopt a track-and-hold (T/H) at the frontend to sample its high-speed inputs before the quantization, and 561 thus the frontend T/H often limits the speed and resolution of the O thus the frontend T/H often limits the speed and resolution of the ADCs [1-4]. In addition, a dedicated time for the T/H should be compromised with comparators' operation time out of the given $\widehat{\mathfrak{S}}$ sampling period. This work presents a 6-bit 5.12 GS/s flash ADC with T/H-embedded dynamic preamplifier. Without having a dedicated = I/H-embedded dynamic preamplifier. Without having a dedicated \cong T/H, the first preamplifiers sample the input signal at the output and then the amplified signal is transferred to the subsequent stage within one clock period in a pipeline fashion. The dynamic preamplifiers consist of two stages. Each preamplifier stage is interpolated by a factor of 2, thus resulting in 4× interpolated preamplifiers for 6-bit flash ADC. Consequently, the prototype ADC achieves an SNDR of 02022 32.97dB and SFDR of 41.52dB at 5.12 GS/s.

Fig. 1 shows the operational principle of the proposed flash ADC. 8 Compared to the conventional flash ADC, the frontend T/H is eliminated and the first dynamic preamplifier takes over this role. The -5/22/ required timing for the preamplifiers and latches can be relaxed, as the T/H takes a certain amount of time to sample high-speed input signals. The first preamplifier is based on a dynamic amplifier. Before 5 amplification, the sampling capacitor (Cs) at the preamplifier output -6654is pre-charged to the V_{DD} via reset switch R₁. During amplification $(\phi_1=1)$, it draws the output current I_B from the C_S, which is proportional to the voltage difference between the input signal VIN and the reference signal VREF. After the sampling at the preamplifier output, the signal at the Cs has a gain of A and is fed to the subsequent stages. This can relax the timing and gain requirements of the following latches.

g Fig. 2 shows the simplified ADC block diagram, which is based on a 4x interpolated flash ADC structure using pipelined dynamic preamplifiers and latches. Before the start of amplification (1), the output nodes of the preamplifier (XP and XN) are reset to VDD. During the ϕ_1 phase (2), the first dynamic preamplifier brings the X_P and X_N down to the signal level proportional to VIN-VREF and the second preamplifier outputs (Y_P and Y_N) are reset to V_{DD}. At the end of ϕ_1 phase, the signal at the first preamplifier output is sampled on the $\frac{1}{2}$ sampling capacitor (~5 fF) with a voltage gain of about 3.5. This sampled signal is applied to the second preamplifier during the ϕ_2 phase (③) so that Y_P and Y_N are set to a different level proportional $\frac{1}{2}$ phase ((3)) so that YP and TN are set to a summary set of a summary $\frac{1}{2}$ to XP and XN. Finally, the strong-arm latch performs the signal $\stackrel{\scriptstyle{\square}}{\cong}$ quantization during the ϕ_1 phase. Considering the sampling $\stackrel{\scriptstyle{\square}}{\cong}$ frequency of 5.12GHz, the total conversion time (1+2+3) must be $\frac{1}{3}$ kept within 195ps and the associated clocks are generated with an $\frac{1}{3}$ on-chin clock generated from the spectrum of the spectr on-chip clock generator from an external master clock. The sampling capacitors (C_{P1} and C_{P2}) at the outputs of the preamplifiers are realized with the interstage metal line and the parasitic junction capacitor. To reduce the number of preamplifiers, 2x interpolation is adopted in each preamplifier stage and 4x interpolation can then be implemented in this work. Therefore, for a 6-bit implementation, the flash ADC consists of 16 first-preamps, 32 second-preamps, and 64 latches. These comparators are followed by the bubble corrector and the thermometer-to-binary encoder. Finally, the 6-bit binary code is decimated by 4096 and delivered to an output buffer.

The most critical block of the proposed flash ADC is the first dynamic preamplifier and its schematic is shown in Fig. 3(a). To maximize the ADC's input bandwidth, small input transistors are used for the

preamplifier and the associated offsets are resolved by the foreground offset calibration. A binary-weighted array of a reference input pair (VREFP and VREFN) steers the output current by Code [0:63], resulting in an offset between ±14mV with a 0.22mV step. The comparator can be divided into two groups for calibration. One is the main branch where the second preamplifier and latch have their own first preamplifier. The other is an interpolated branch where the second preamplifier and latch receive shared inputs from adjacent preamplifiers. In this work, only the main branch is calibrated because the offset of the interpolated branches would be suppressed by the main branches whose offsets are eliminated by the calibration, and this can minimize the number of calibration code registers. For area efficiency, one of 16 data from the main branches is selected and used as an up/down flag of a counter, as shown in Fig. 3(b). During the calibration, register selector and code selector change the connection between the counter and the corresponding code register. The counter output increases (or decreases) until it toggles, which means that the total offset of the target sub-unit is less than 1-LSB of the calibration code. The first sub-units to be calibrated are latches since the latch outputs are used in the calibration logic. When calibration starts, the latch inputs are switched to a reference voltage V_{CAL} and the latch outputs are sent to the calibration logic. After the latch calibration, the second and the first preamplifier are sequentially calibrated in the same manner. Finally, 48 set of 6-bit calibration codes are applied to sub-units in the main branches.

The prototype ADC is fabricated in a 28 nm CMOS process, and the ADC core and the calibration logic occupy 0.041mm² and 0.040mm² respectively (Fig. 7). The ADC core consumes 41mW from a 1.2V supply. Differential input paths are routed symmetrically to minimize the skew between them, and the ADC's input capacitance is about 100fF. Fig. 4 shows the measured power spectrum density at the sampling frequency of 5.12 GS/s. Without the calibration, the measured SNR and SFDR are 32.0 dB and 39.8 dB, respectively with an 80MHz input signal, deteriorating to 28.7 dB and 35.6 dB with a near Nyquist input. After calibration, the measured SNDR and SFDR are improved to 34.2 dB and 43.3 dB with the same lowfrequency input, and to 33.0 dB and 41.5 dB with a near Nyquist input. Fig. 5 (a) and (b) shows the measured DNL and INL, achieving +0.65/-0.5 LSB and +0.7/-0.52 LSB, respectively. Fig. 5(c) shows the measured SNR and SNDR over different input frequencies at 5.12GS/s. Up to the Nyquist input frequency, SNDRs and SFDRs stay above 32.9dB and 40.7dB, respectively. It also demonstrates the input bandwidth of ~3GHz. Fig. 5(d) shows the measured SNDR and SFDR over the different sampling frequencies, maintaining above 32.9dB and 40dB. Fig. 6 shows the performance summary of this work and the comparison with other state-of-the-art flash ADCs. This work achieves a FoM of 216.6fJ/c.-s at 5.12GS/s. Compared to [1, 3, 4], this work achieves a higher sampling rate and signal bandwidth without explicit T/H. In contrast to [2, 4], this work includes an on-chip offset calibration logic that requires a small active area of 0.04mm². These results demonstrate that the proposed flash ADC with the T/H-embedded dynamic preamplifier is effective up to a sampling rate of 5.12GS/s.

Acknowledgement:

This work was supported by Samsung Electronics.

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IEEE Asian Solid-State Circuits Conference November 6-9, 2022/Taipei, Taiwan



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